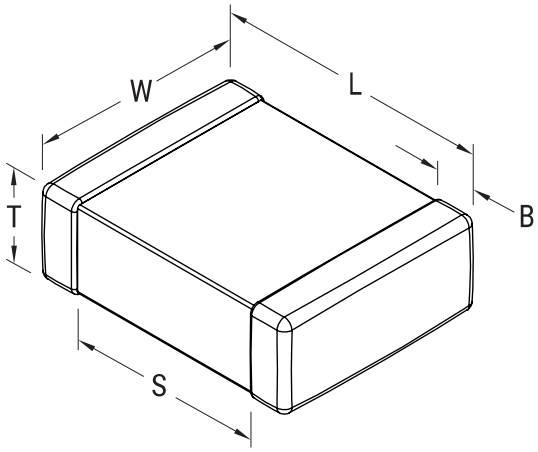
C1206X309C3TAC7210

SMD Comm X8G HT150C Flex, Ceramic, 3 pF, +/-0.25 pF, 25 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206 / 3216



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
Typical Component Weight	17 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
T	0.78mm +/-0.20mm
S	1.5mm MIN
B	0.6mm +/-0.25mm
Case Code (EIA / mm)	1206 / 3216

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

Specifications	
Capacitance	3 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.25 pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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